



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB80N04S3-03		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000366322						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1464.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.365	0.43	0.43	4347	4347
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		582	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.15	58.23	581728	582485
wire	non noble metal	aluminium	7429-90-5	6.718	0.46	0.46	4589	4589
encapsulation	organic material	carbon black	1333-86-4	8.768	0.60		5989	
	plastics	epoxy resin	-	96.446	6.59		65875	
	inorganic material	silicondioxide	60676-86-0	479.307	32.74	39.93	327379	399243
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6596	6596
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	non noble metal	tin	7440-31-5	0.076	0.01		52	
	noble metal	silver	7440-22-4	0.095	0.01		65	
	non noble metal	lead	7439-92-1	3.612	0.25	0.27	2467	2584
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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